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TI Relaxation-resistant copper alloys
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SO Jpn. Kokai Tokkyo Koho, 4 pp.
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AB Cu alloys containing 0.4-4.0% Ni and 0.1-1.0% Si are soln. treated at 700° to give $\geq 5\mu$ grain size, and optionally aged at 350-700° or cold-worked with $\leq 95\%$ reduction and then aged at 350-700°. Ingot of Cu -0.60% Ni-0.15% Si alloy was hot-rolled at 950° and quenched to manufacture plate 7 mm thick. The trimmed plate was cold-rolled into 1.5 mm thick sheet, aged for 3 h at 420°, cold-rolled, and then heat-treated for 1 min at 600°. Stress relaxation was 15% after 1000 h at 80% of yield strength.